



Data Sheet

Customer:	
Part No:	CL-SP157RGB-02
Sample No:	
Description:	3227 SMD Full Color
Item No:	

Customer					
Check Inspection Approval Date					







Features

3.2mmx2.7mm SMT LED,1.0mm THICKNESS.

_LOW POWER CONSUMPTION.

_WIDE VIEWING ANGLE.

_IDEAL FOR BACKLIGHT AND INDICATOR.

_VARIOUS COLORS AND LENS TYPES AVAILABLE.

_PACKAGE: 3000 PCS / REEL.

_RoHS COMPLIANT.

Description

The Blue source color devices are made with GaN on Sapphire Light Emitting Diode.

The Green source color devices are made with InGaN on SiC Light Emitting Diode.

The Hyper Orange source color devices are made with DH InGaAIP on GaAs substrate Light Emitting Diode.

Static electricity and surge damage the LEDS.

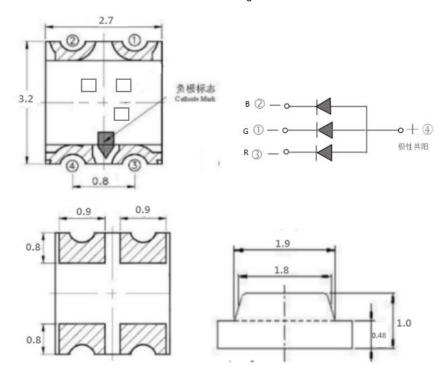
It is recommended to use a wrist band or

anti-electrostatic glove when handling the LEDs.

All devices, equipment and machinery must be electrically grounded.

Emitting Diode.

Package Dimensions



Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.1 (0.004")$ unless otherwise noted.
- 3. Specifications are subject to change without notice.





Selection Guide

			lv (mcd)		Viewing
Part No.	Dice	Lens Type	@ 20mA		Angle
			Min.	Тур.	2 θ 1/2
CL-SP157RGB-02	BLUE (GaN)		100	200	
	GREEN (InGaN)	WATER CLEAR	400	600	120
	RED (InGaAIP)		100	200	

Note:

1. θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

Electrical / Optical Characteristics at Ta=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
		Blue	464	472		
λD	Dominant Wavelength	Green	518	530	nm	IF=20mA
		Red	615	630		
	Spectral Line Half-width	Blue	25			
Δλ1/2		Green	38		nm	IF=20mA
		Red	20			
	Capacitance	Blue	100			
С		Green	45		pF	VF=0V;f=1MH
		Red	25			z
		Blue	2.9	3.4		
VF	Forward Voltage	Green	2.9	3.4	V	IF=20mA
		Red	1.8	2.2		
	Reverse Curren	Blue		5		
IR		Green		5	uA	VR = 5V
		Red		5		

Absolute Maximum Ratings at Ta=25°C

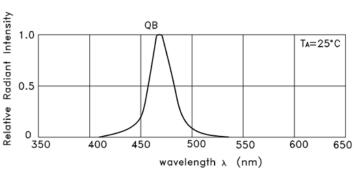
Parameter	Blue	Green	Red	Units
Power dissipation	135	135	75	mW
DC Forward Current	30	30	30	mA
Peak Forward Current [1]	135	135	80	mA
Reverse Voltage	5	5	5	V
Operating/Storage Temperature	-40°C To +85°C			

Note:

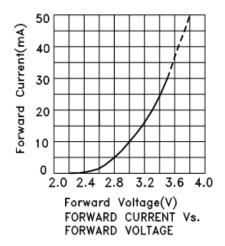
1. 1/10 Duty Cycle, 0.1ms Pulse Width.

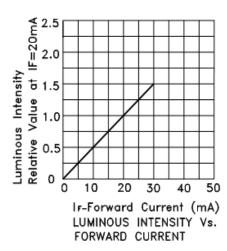


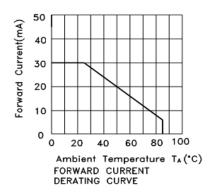


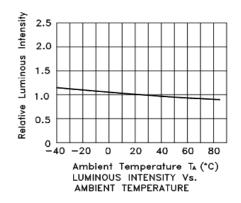


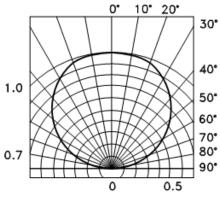
RELATIVE INTENSITY Vs. WAVELENGTH







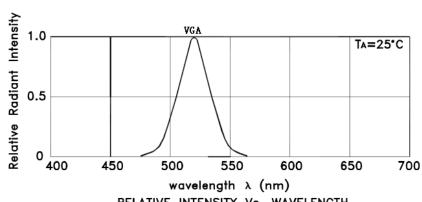




SPATIAL DISTRIBUTION

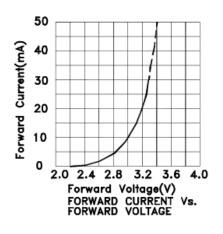


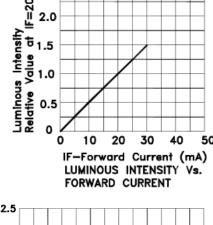


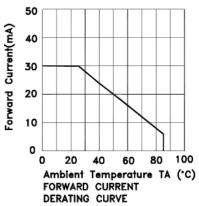


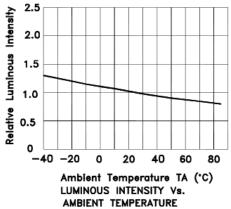
RELATIVE INTENSITY Vs. WAVELENGTH

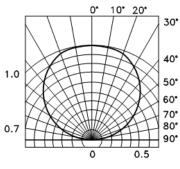
2.5







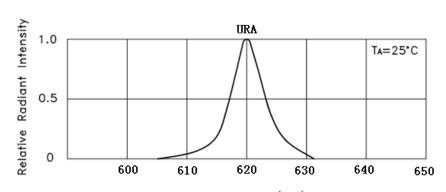


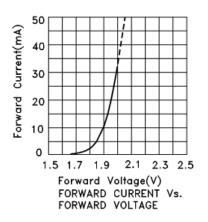


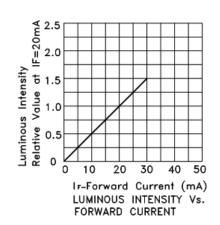
SPATIAL DISTRIBUTION

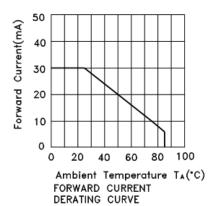


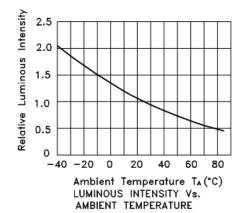


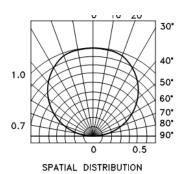












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RELIABILITY

Test Items and Results

Test	items and Results					
NO.	Test Item	Reference Standard	Test Conditiong	(Hours/ Cycles)	Sampl e	Number of Damaged
1	Temperature Cycle	JEITA ED-4701	-40°C~25°C~100°C~25°C 30 min 5 min 30 min 5 min	100 Cycles	50	0/50
2	Thermal Shock	MIL-STD-2 02G	-40°C ~100°C 15 min 15 min	500 Cycles	50	0/50
3	High Temperature Storage	JEITA ED-4701 200 201	Ta=100°C	1000 Hours	50	0/50
4	Low Temperature Storage	JEITA ED-4701 200 201	Ta=-40°C	1000 Hours	50	0/50
5	Room Temperature Life Test		T₁=25±5°C I _F =20mA	1000 Hours	50	0/50
6	High Temperature High Humidity Life Test		Ta=60°C RH=85% Ir=20mA	1000 Hours	50	0/50
7	Solderability (Reflow Soldering)	JEITA ED-4701 300 303	T_{sol} =235°C±5°C,5 sec (Using Flux, Lead Solder)	1 time, 5 sec	10	0/10
8	Resistance to Soldering Heat (Reflow Soldering)	JEITA ED-4701 300 301	T _{sol} =260°C,10 sec Pre Treatment: 35°C 95%RH 96 Hrs	2 time, 10 sec	10	0/10

The above test items such as differences or special customer specific requirements according to the actual situation in accordance with the requirements of customers to try the requirements with the customer, the customer is not required by our test standard test. Different products using different current test.





5. Cautions

(1) Soldering Conditions

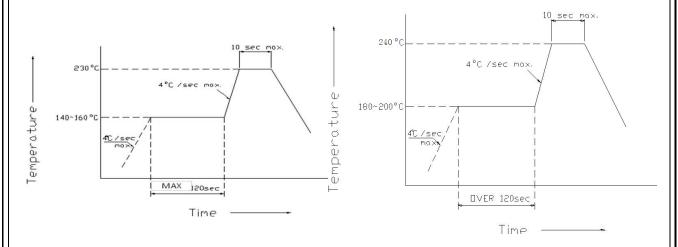
Number of reflow process shall be less than 2 times and cooling process to normal temperature is required between first and Second soldering process.

(Recommended soldering conditions)

回流	焊接 Reflow Solder:	手工焊接		
预热温度 Pre-heat	有铅 Lead Solder	无铅 Lead-free Solder	温度 Temperature 焊接时间 Soldering	350° C Max. 3 sec. Max.
预热时间 Pre-heat time 峰值温度 Peak temperature 焊接时间 Soldering time 条件Condition	140 ~ 160° C 120 sec. Max. 230° C Max. 10 sec. Max. 参考下图	180 ~ 200° C 120 sec. Max. 240° C Max. 10 sec. Max. 参考下图	time	(one time only)

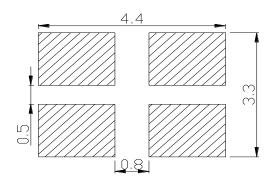
(Lead Solder)

(Lead-Free Solder)



Recommended Soldering Pattern

(Units: mm)







(2) Static Electricity

It is recommended that a wrist band or an anti-electrostatic glove be used when handling the LEDs.

All devices, equipment and machinery must be properly grounded.

Damaged LEDs will show some unusual characteristics such as the forward voltage becomes lower, or the LEDs do not light at the low current. Criteria: (VF > 2.0V at IF=0.5mA)

(3) Moisture Proof Package

It is recommended that moisture proof package be used.

(4)Cautions:

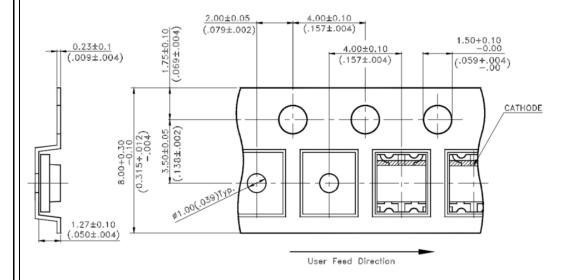
- 4.1.Please check if there is air leak before opening the package, if so, please return the goods back to take drying process for later using.
- 4.2 Products can be used within 15days after packaging, after that, they must be:
 - 4.2.1 Soldered within 24 hrs
 - 4.2.2 Used in the condition: 30°C within and 60%RH below
 - 4.2.3 Stored in 30%RH for moisture below.
- 4.3. Products cannot be used for and over 15days after being packaged unless opening the package and take drying our process in 85°C/6H.
- 4.4.Products not be used for or over 60days after being packaged please return back to take drying out and packaging process for forward using.



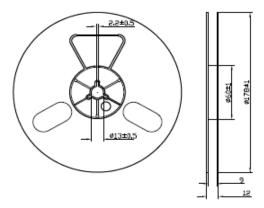


PACKAGING

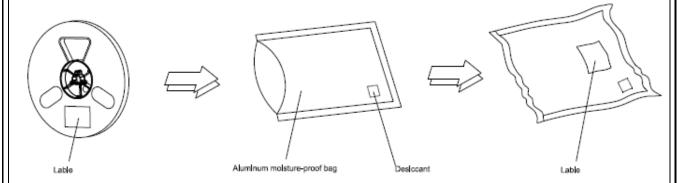
The LEDs are packed in cardboard boxes after taping.



Reel Dimensions



Moisture Resistant Packaging



Note:The tolerances unless mentioned is ±0.1mm,Unit:mm